

LNPTM STAT-KONTM COMPOUND KE002

KC-1002

DESCRIPTION

LNP STAT-KON KE002 compound is based on POM (Acetal) copolymer resin containing 10% Carbon Fiber. Added feature of this material is: Electrically Conductive.

GENERAL INFORMATION

Applications	Fuel Handling, Weaving Machine
Features	Electrically Conductive, Carbon fiber filled, High stiffness/Strength, No PFAS intentionally added
Fillers	Carbon Fiber
Polymer Types	Acetal (POM) Copolymer
Processing Techniques	Injection Molding
Regional Availability	Europe, Asia, Americas

INDUSTRY

Electrical and Electronics
Industrial

SUB INDUSTRY

Electronic Components
Material Handling

TYPICAL PROPERTY VALUES

Revision 20231109

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL ⁽¹⁾			
Tensile Stress, break, 5 mm/min	104	MPa	ISO 527
Tensile Strain, break, 5 mm/min	2	%	ISO 527
Tensile Modulus, 1 mm/min	7900	MPa	ISO 527
Flexural Stress	154	MPa	ISO 178
Flexural Modulus, 2 mm/min	7000	MPa	ISO 178
Tensile Stress, brk, Type I, 5 mm/min	106	MPa	ASTM D638
Tensile Strain, brk, Type I, 5 mm/min	2.4	%	ASTM D638
IMPACT ⁽¹⁾			
Izod Impact, notched 80*10*4 +23°C	5	kJ/m ²	ISO 180/1A
Izod Impact, unnotched 80*10*4 +23°C	20	kJ/m ²	ISO 180/1U
Izod Impact, unnotched, 23°C	374	J/m	ASTM D4812
Izod Impact, notched, 23°C	42	J/m	ASTM D256
THERMAL ⁽¹⁾			
HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm	158	°C	ISO 75/Af
CTE, 23°C to 60°C, flow	3.10E-05	1/°C	ISO 11359-2
CTE, 23°C to 60°C, xflow	1.15E-04	1/°C	ISO 11359-2
PHYSICAL ⁽¹⁾			
Density	1.42	g/cm ³	ISO 1183
Specific Gravity	1.43	-	ASTM D792
Mold Shrinkage, flow, 24 hrs ⁽²⁾	0.5 – 0.7	%	ASTM D955

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CHEMISTRY THAT MATTERS™

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
Mold Shrinkage, xflow, 24 hrs ⁽²⁾	1 – 3	%	ASTM D955
ELECTRICAL ⁽¹⁾			
Surface Resistivity ⁽³⁾	1.E+02 – 1.E+05	Ω	ASTM D257
INJECTION MOLDING ⁽⁴⁾			
Drying Temperature	80	°C	
Drying Time	4	Hrs	
Melt Temperature	200 – 215	°C	
Front - Zone 3 Temperature	210 – 220	°C	
Middle - Zone 2 Temperature	195 – 205	°C	
Rear - Zone 1 Temperature	175 – 190	°C	
Mold Temperature	80 – 110	°C	
Back Pressure	0.2 – 0.3	MPa	
Screw Speed	30 – 60	rpm	

- (1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.
- (2) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.
- (3) Measurement meets requirements as specified in ASTM D4496.
- (4) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

ADDITIONAL PRODUCT NOTES

No PFAS intentionally added: The grade listed in this document does not contain PFAS intentionally added during Seller's manufacturing process and is not expected to contain unintentional PFAS impurities. Each user is responsible for evaluating the presence of unintentional PFAS impurities.

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